

RoHS Compliance of Products



This is to certify that the product types listed in the enclosed table conform with the

Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive) (last Amendment with Directive 2015/863/EU)

The listed product types do not contain mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB), polybrominated diphenyl ethers (PBDE), bis(2-ethylhexyl) phthalate (DEHP), butyl benzyl phthalate (BBP), dibutyl phthalate (DBP) and diisobutyl phthalate (DIBP). But the listed products can contain lead / a lead component which is explained as follows:

Lead (Pb) / lead components:

The sensor types can contain lead in form of lead oxide (PbO) which is combined with / fixed in the glass layers of the sensor element. According to figure 7c-I of the annex of the directive 2011/65/EU the use of "lead in glass of ... electronic components" is exempted from the requirements of Article 4(1) of the directive.

Under consideration of the explained exemption and under consideration of quantity limits for restricted materials the listed product types are in compliance with the EU directive 2011/65/EU.

The declaration is only valid for standard sensor elements. Any change of the listed product types like for example extension with other lead material and/or housing and/or insulation and/or other changes made by Heraeus Nexensos GmbH and/or made by the customer itself requires a new evaluation of the final sensor type / article for compliance with the RoHS directive.

Heraeus Nexensos GmbH

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Table of standard sensor elements

Type	Connection Material	RoHS exemption	Type	Connection Material	RoHS exemption
C 220	AgPd	None	C 416	AuPd	7c-I
C 420	AgPd	7c-I	C 420	NiPt	7c-I
HL 220	NiCr-Pt	None	HM 220	Pd alloy-Pt	None
HDA 420	Pt	None	HD 421	Pt	None
HA 420	Pt	None			
L 220	AgPd	7c-I	L 410 ax	AgPd	7c-I
L 416	AgPd	7c-I	L 420	AgPd	7c-I
L 540	AgPd	7c-I	L 1020	AgPd	7c-I
LN 222	NiAg	None			
M 213	NiPt	7c-I	M 219	NiPt	7c-I
M 220 / 222	NiPt	7c-I	M 310	NiPt	7c-I
M 416	NiPt	7c-I	M 419	NiPt	7c-I
M 422	NiPt	7c-I	M 620	NiPt	7c-I
M 1020	NiPt	7c-I			
MN 220 / 222	Ni	None	MN 420 / 422	Ni	None
MH 220	AuPd	None	MH 416	AuPd	None
MH 420	AuPd	None			
MR 828	NiPt	7c-I	MR 845	NiPt	7c-I
PCB 1325	Tinned Cu pads	None	PCB 2225	Tinned Cu pads	None
PCB 2230	Tinned Cu pads	None	PCB 2236	Tinned Cu pads	None
PCB 2240	Tinned Cu pads	None			
SMD-V 0603	Tinned edge metallization	None	SMD-V 0805	Tinned edge metallization	None
SMD-V 1206	Tinned edge metallization	None			
SMD 0603 FC	AgPt metallization	None	SMD 0805 FC	AgPt metallization	None
TO92	Sn plated Cu alloy	7c-I	SOT 223	Sn plated Cu alloy	7c-I